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Resin-moulded semiconductor hybrid module and manufacturing method thereof

Patent Number: EP0936671

Publication date: 1999-08-18

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Requested Patent: ☐ EP0936671

Application Number: EP19990101733 19990211

Priority Number (s): JP19980029491 19980212


IPC Classification: H01L25/16; H01L23/433

EC Classification: H01L25/16H, H01L23/433E

Equivalents: ☐ JP11233712, ☐ US6291880

Cited Documents: EP0774782; US5699609; US5077595; JP8298299

Abstract

A semiconductor device includes a main circuit part having a semiconductor device formed on an electrode plate (13) of a lead frame and a control circuit part having protective functions, which is integrally molded by a resin mold part (30) into an integral mold structure. 

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